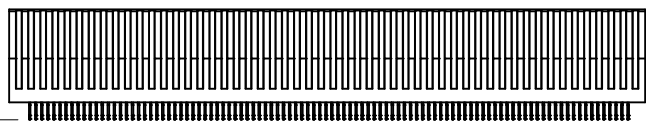


PART NUMBER	VERSION	BAY 1/BAY 2	TOTAL CIRCUITS	DIM A	SALES DRAWING (SEE NOTE 8)
170673-2278	2 BAY	146/132	278	118.63	SD-170673-2278
170673-1200	1 BAY	200	200	84.20	SD-170673-1200
170673-2108	2 BAY	86/22	108	50.63	SD-170673-2108
170673-2080	2 BAY	52/28	80	39.43	SD-170673-2080
170673-1046	1 BAY	46	46	22.60	SD-170673-1046

2 BAY EDGELINE



1 BAY EDGELINE



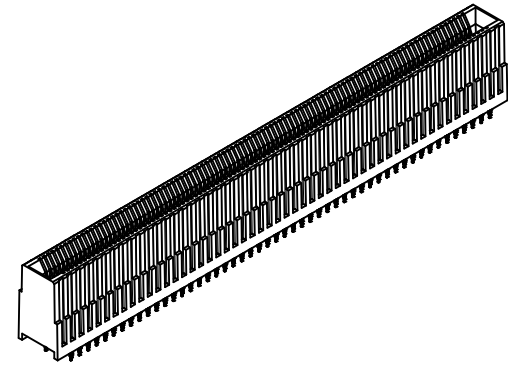
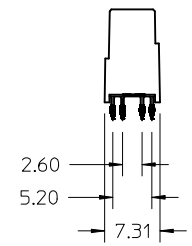
LAST CIRCUIT



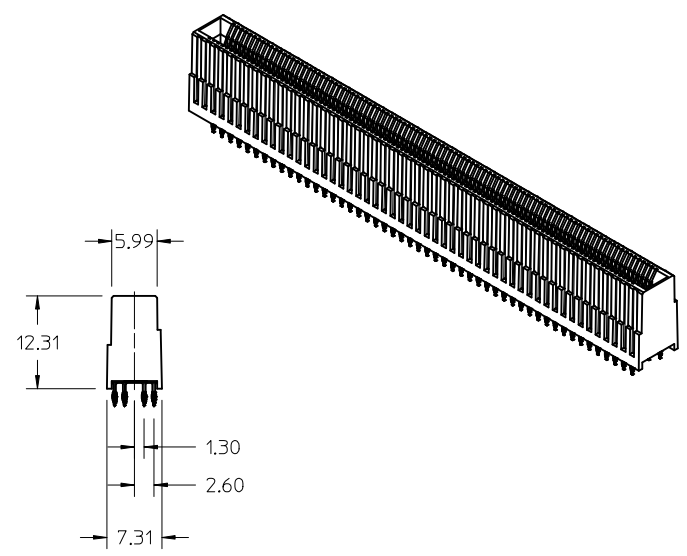
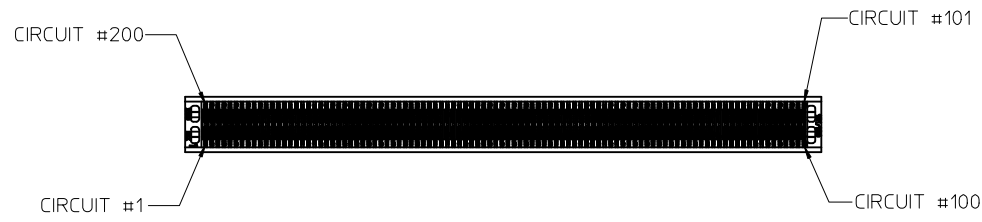
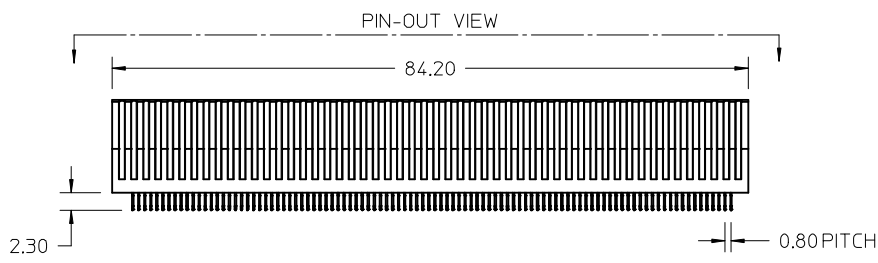
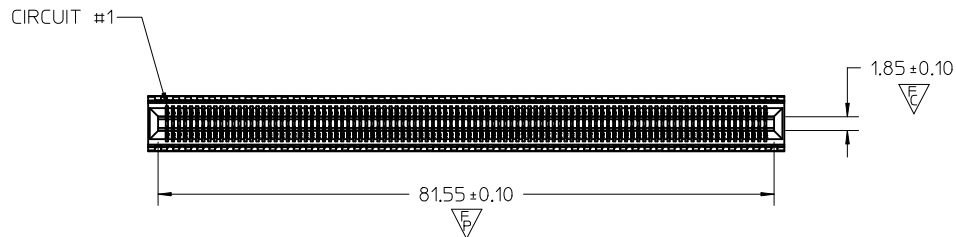
FIRST CIRCUIT

NOTES:

- MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
- FINISH:
CONTACT AREA: HARD GOLD -0.76μm MIN OVER 3.80μ NICKEL
COMPLIANT AREA: TIN - 0.76/1.52μm OVER NICKEL
- REFER TO PS-75594-999 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIROMENTAL SPECIFICATIONS.
- PROCESSING: PRESSFIT TO PC BOARD.
- MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
- PRODUCT IS ELV AND RoHS COMPLIANT. LEVEL OF COMPLIANCE: 6/6
ALL BANNED SUBSTANCES ARE REMOVED:
Pb (LEAD)
HEXAVALENT CHROMIUM (CrVI)
CADMIUM
MERCURY
POLYBRMINATED BIPHENYL (PBB)
POLYBROMINATED DIPHENYL ETHER (PBDE)
- THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002
- FOR EDGECARD AND MOUNTING PCB LAYOUT DETAIL SEE CORRESPONDING SALES DRAWING.



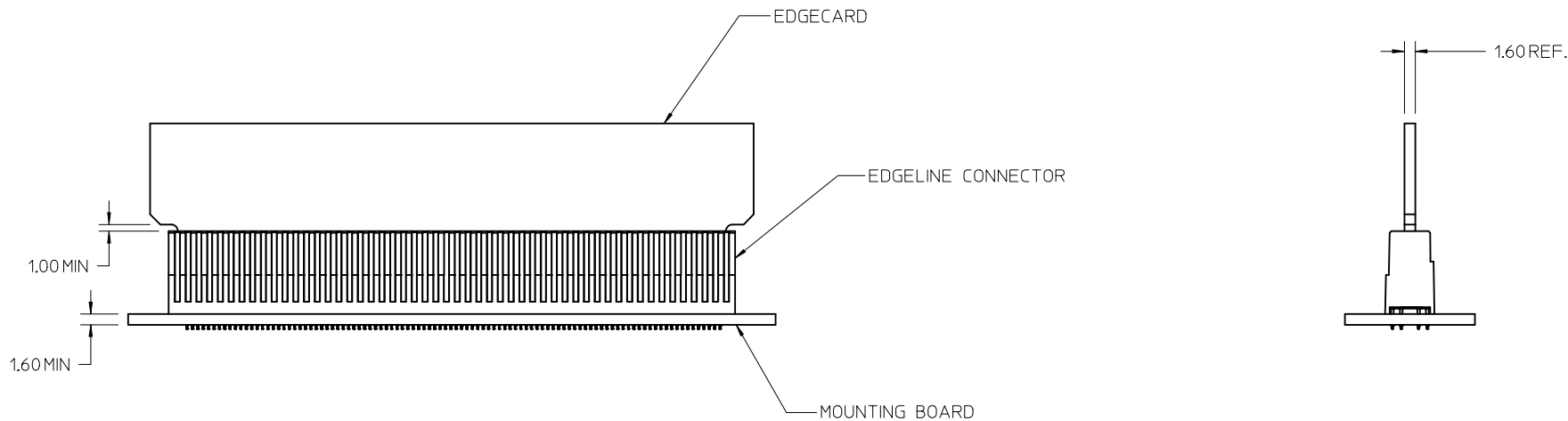
RELEASED REV A EC NO: UCP2011-2702 DRWNG: DROSCA 2011/03/07 CHKD: JCOMERC I 2011/03/28 APPR: JCOMERC I 2011/03/28	DESCRIPTION REV 0 0 0	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm INCH	DRAWN BY DATE DROSCA 2010/06/22	TITLE EDGELINE 12.5GB 0.062*PCB 0.8MM PITCH		
			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	CHECKED BY DATE JCOMERC I 2010/06/22			
			ANGULAR ±1/2°	APPROVED BY DATE JCOMERC I 2010/10/25			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-170673-0001	SHEET NO. 1 OF 1		
			SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



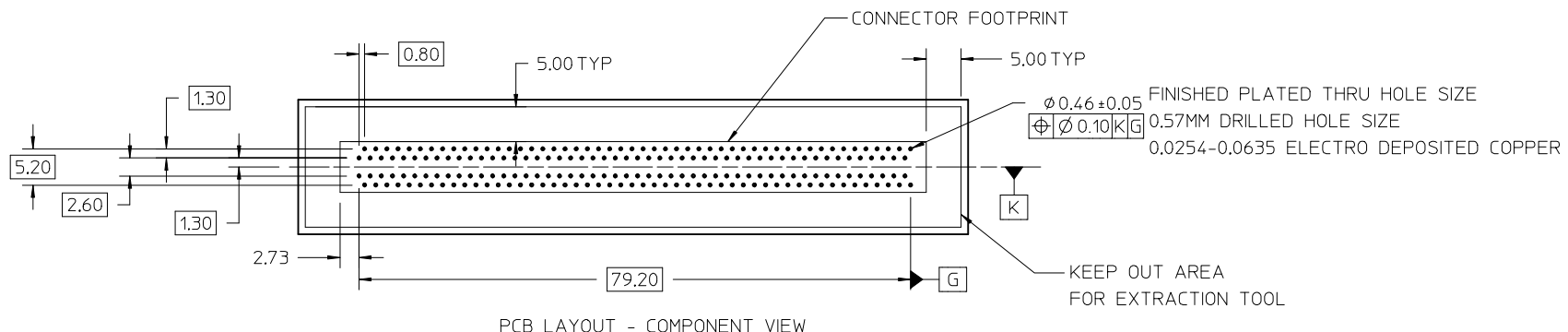
- NOTES:
- MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
 - FINISH:
CONTACT AREA: HARD GOLD -0.76μm MIN OVER 3.80μm NICKEL
COMPLIANT AREA: TIN - 0.76/1.52μm OVER NICKEL
 - REFER TO PS-75594-999 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
 - REFER TO PK-76693-900 FOR ALL PACKAGING SPECIFICATIONS.
 - PROCESSING: PRESSFIT TO PC BOARD.
 - MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002

CORRECT EDGE CARD WIDTH TOLERANCE IEC NO: UCP2016-4620 DRAWINGS CHKD: APPR:DMC/GOMAN	2016/06/02	2016/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DESCRIPTION		▽=0 ▽=1 ▽=1	mm INCH	DRAWN BY GES	DATE 2014/09/26	TITLE EDGE LINE 12.5GB 200CKTS 0.062"PCB 0.8MM PITCH	
	REV			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.13 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	CHECKED BY	DATE		
				ANGULAR ± 2 °	APPROVED BY	DATE		
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. 1706731200	DOCUMENT NO. SD-170673-1200	SHEET NO. 1 OF 4	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

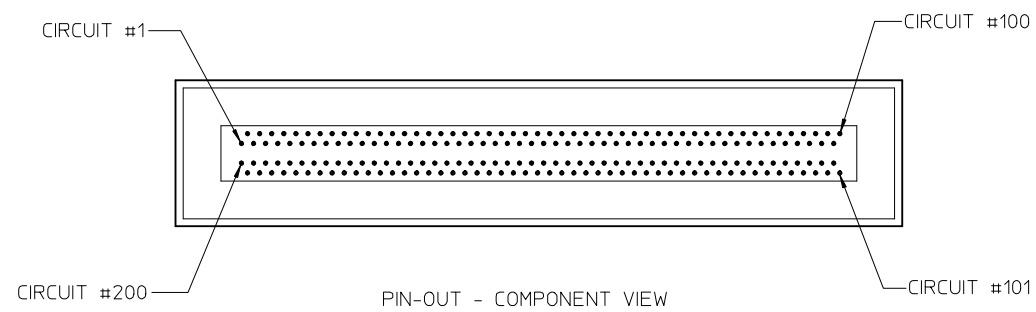
EDGE LINE CONNECTOR BOARD MOUNTING



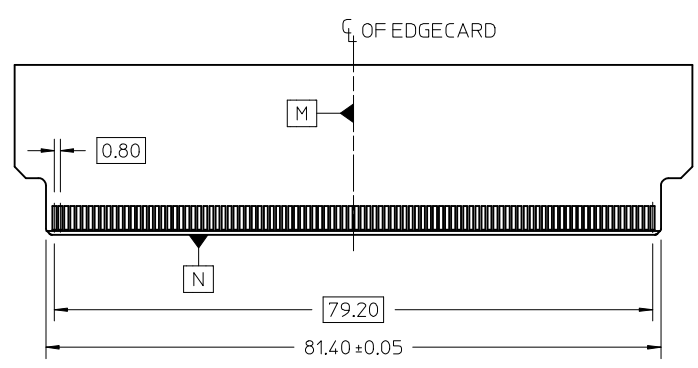
SEE SHEET 1 EC NO: UCP2016-4620 2016/06/02 DRWNGES CHKD: APPR:DMCGOWAN 2016/06/13 DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION																			
	▽=0 ▽=0 ▽=0	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.13</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> <tr> <td>0 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.13	± ---	1 PLACE	± 0.25	± ---	0 PLACE	± ---	± ---	ANGULAR ± 2 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY GES DATE 2014/09/26 CHECKED BY DATE APPROVED BY DATE	TITLE EDGE LINE 12.5GB 200CKTS 0.062*PCB 0.8MM PITCH		
		mm	INCH																						
	4 PLACES	± ---	± ---																						
3 PLACES	± ---	± ---																							
2 PLACES	± 0.13	± ---																							
1 PLACE	± 0.25	± ---																							
0 PLACE	± ---	± ---																							
MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-170673-1200		molex																						
SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					SHEET NO. 2 OF 4																			



PCB LAYOUT - COMPONENT VIEW

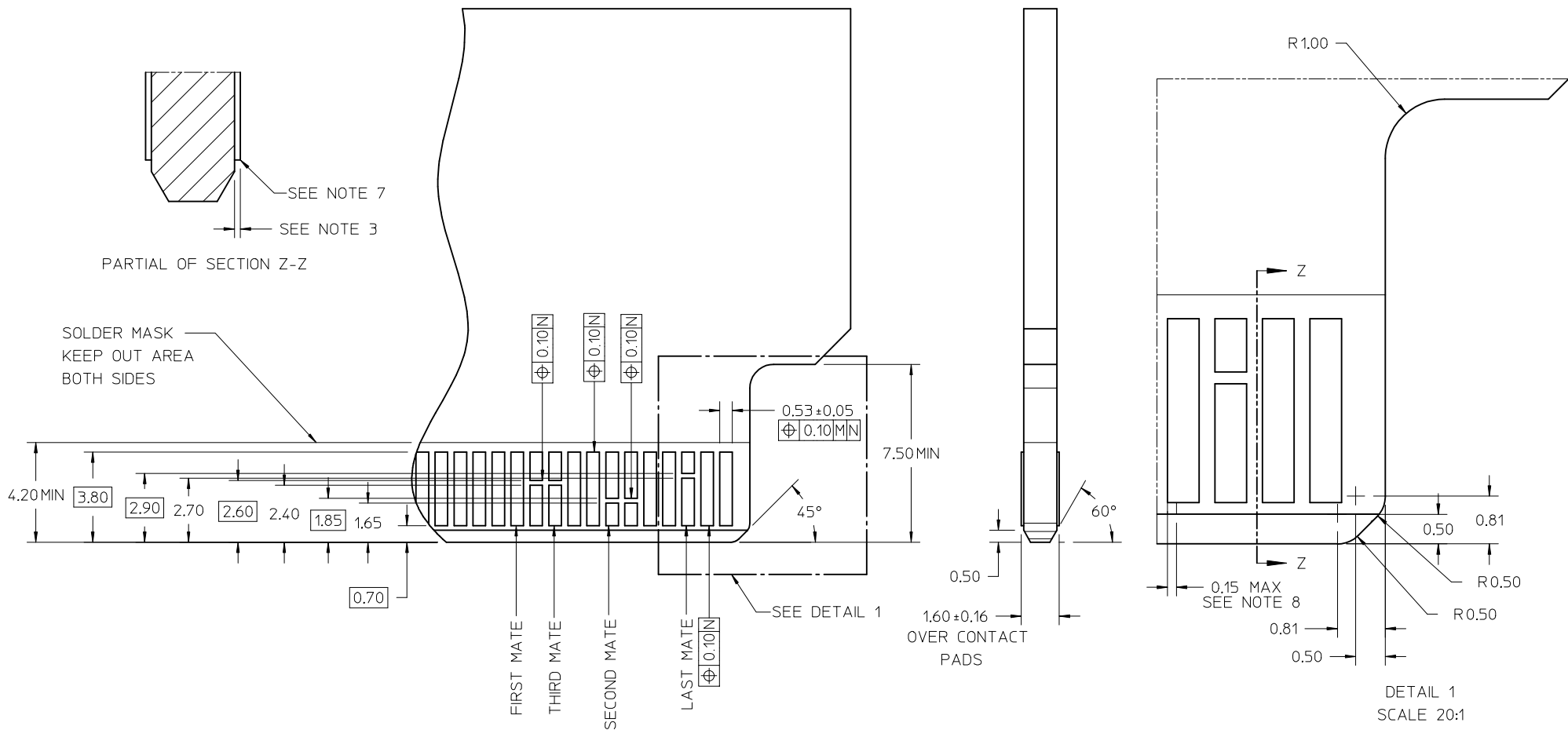


PIN-OUT - COMPONENT VIEW



SEE SHEET 1 EC NO: UCP2016-4620 DRWNGES 2016/06/02 CHKD: APPR:DMCGOWAN 2016/06/13 REV:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla = 0$	mm INCH	MM ONLY	2:1	METRIC	
	$\nabla = 0$	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	$\nabla = 0$	3 PLACES ± --- ± ---	GES 2014/09/26	EDGE LINE 12.5GB 200CKTS 0.062*PCB 0.8MM PITCH		
		2 PLACES ± 0.13 ± ---	CHECKED BY DATE	MATERIAL NO. DOCUMENT NO.		
		1 PLACE ± 0.25 ± ---	APPROVED BY DATE	SEE SHEET 1 SD-170673-1200		
		0 PLACE ± --- ± ---		SHEET NO. 3 OF 4		
		ANGULAR ± 2 °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

MODULE EDGE CARD CONTACT DETAIL



MATING PCB NOTES:

- CONNECTOR LAND CONDITIONS SHALL MEET THE MOST CURRENT REVISION OF PCB SPECIFICATION IPC-6012C-2010 SECTION 3.5.4.4.
- DIMENSIONS APPLY TO LANDS ON BOTH SIDES OF THE BOARD.
- THE THICKNESS OF THE OUTER METAL LAYERS, INCLUDING FOIL, COPPER PLATING, AND THE PROTECTIVE SURFACE FINISH, SHALL BE 0.066mm MAX.
- CHAMFER ROUGHNESS NOT TO EXCEED 3.17 MICROMETERS.
- CHAMFER PROCESS SHALL NOT DAMAGE THE GOLD EDGE LANDS.
- EDGE CARD CHAMFER NOT TO GO THRU GOLD LANDS.
- 0.03mm MAX PLATING OVERHANG ON ALL GOLD LAND EDGES.
- MOLEX RECOMMENDS NO TIE-BARS ON THE LEADING EDGE OF THE GOLD LAND. IF TIE-BARS ARE USED, THEY SHALL BE PLACED TO ONE SIDE OF THE GOLD LAND. APPLIES TO ALL GOLD LANDS.

SEE SHEET 1 EC NO: UCP2016-4620 DRWNGES 2016/06/02 CHKD: APPR:DMCGOWAN 2016/06/13 REVISIONS DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 8:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY GES	DATE 2014/09/26	TITLE EDGELINE 12.5GB 200CKTS 0.062"PCB 0.8MM PITCH	
	▽=0	4 PLACES ± --- ± ---	CHECKED BY	DATE	molex DOCUMENT NO. SD-170673-1200 SHEET NO. 4 OF 4	
	▽=0	3 PLACES ± --- ± ---	APPROVED BY	DATE		
		2 PLACES ± 0.13 ± ---	MATERIAL NO. SEE SHEET 1			
		1 PLACE ± 0.25 ± ---	SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		0 PLACE ± --- ± ---				
		ANGULAR ± 2 °				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				